### N-Channel 20V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low  $r_{DS(on)}$  and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

PRODUCT SUMMARY				
<b>V</b> <sub>DS</sub> <b>(V)</b>	$I_{DS}(V)$ $I_{DS(on)}(\Omega)$ $I_{D}(A)$			
20	$0.058@V_{CS}=4.5V$	4.3		
	$0.082 @V_{CS} = 2.5V$	3.6		

- Low r<sub>DS(on)</sub> provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SC70-6 saves board space
- Fast switching speed
- High performance trench technology

	SC	70-6		$D_{\scriptscriptstyle{1}}$
	Top	View	•	· ·
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рЩ	2	5	<u></u> □ D	, H
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				N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C UNLESS OTHERWSE NOTED)						
Parameter Parameter			Maximum	Units		
Drain-Source Voltage			20	V		
Gate-Source Voltage			±8	V		
Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25°C		4.3			
Continuous Drain Current	$T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$	1D	3.5	A		
Pulsed Drain Current <sup>b</sup>		$I_{DM}$	±20			
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	1.6	A		
D D: : ,: a	$T_A=25^{\circ}C$	D_	1.56	W		
Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C T <sub>A</sub> =70°C	I D	0.81			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Maximum	Units			
Maximum Junction-to-Ambient <sup>a</sup>	t <= 5 sec	D	100	°C/W		
	Steady-State	$R_{THJA}$	166			

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### Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

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Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Static						
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$	0.7			V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			±100	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}$			1	uA
	*D88	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			10	
On-State Drain Current <sup>A</sup>	$I_{D(on)}$	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	10			Α
Drain-Source On-Resistance <sup>A</sup>	r <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 4.3 \text{ A}$			58	mΩ
Diam-Source On-Resistance		$V_{GS} = 2.5 \text{ V}, I_D = 3.6 \text{ A}$			82	
Forward Tranconductance <sup>A</sup>	$g_{\mathrm{fs}}$	$V_{DS} = 10 \text{ V}, I_D = 4.3 \text{ A}$		11.3		S
Diode Forward Voltage	$V_{\mathrm{SD}}$	$I_S = 1.6 \text{ A}, V_{GS} = 0 \text{ V}$		0.75		V
Dynamic <sup>b</sup>						
Total Gate Charge	$Q_{g}$			2.5		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 4.3 \text{ A}$		0.6		nC
Gate-Drain Charge	$Q_{gd}$			1.0		
Turn-On Delay Time	t <sub>d(on)</sub>			8		
Rise Time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, R_L = 15 \Omega, I_D = 1 \text{ A},$		24		
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GEN} = 4.5 \text{ V}$		35		ns
Fall-Time	$t_{\mathrm{f}}$			10		1

#### Notes

- a. Pulse test:  $PW \le 300us duty cycle \le 2\%$ .
- b. Guaranteed by design, not subject to production testing.

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# Typical Electrical Characteristics (N-Channel)

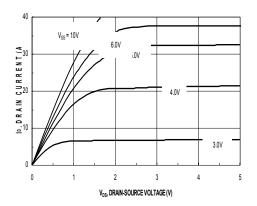


Figure 1. On-Region Characteristics

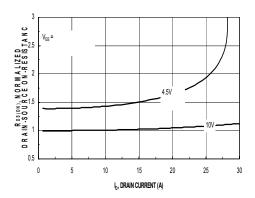


Figure 3. On Resistance Vs Vgs Voltage

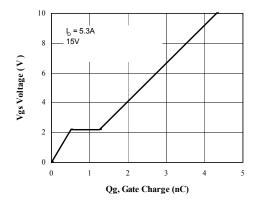


Figure 5. Gate Charge Characteristics

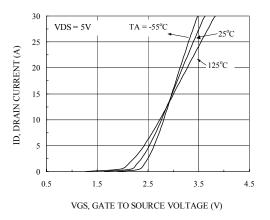


Figure 2. Body Diode Forward Voltage Variation with Source Current and Temperature

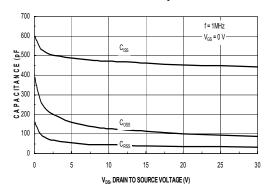


Figure 4. Capacitance Characteristics

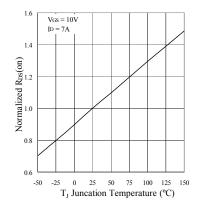


Figure 6. On-Resistance Variation with Temperature

## Typical Electrical Characteristics (N-Channel)

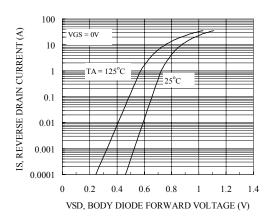


Figure 7. Transfer Characteristics

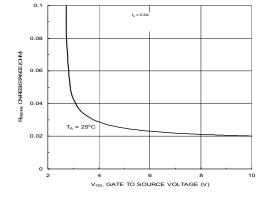


Figure 8. On-Resistance with Gate to Source Voltage

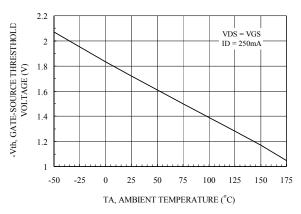


Figure 9. Vth Gate to Source Voltage Vs Temperature

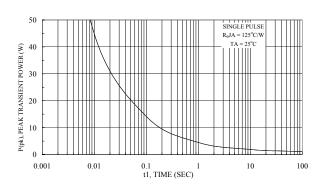
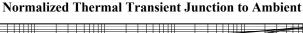


Figure 10. Single Pulse Maximum Power Dissipation



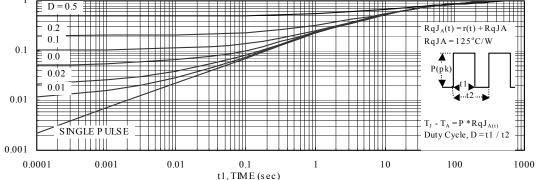


Figure 11. Transient Thermal Response Curve